

Title (en)

APPARATUS AND METHOD FOR TREATING A SUBSTRATE ELECTROCHEMICALLY WHILE REDUCING METAL CORROSION

Title (de)

VORRICHTUNG UND VERFAHREN ZUM ELEKTROCHEMISCHEN BEHANDELN EINES SUBSTRATS BEI GLEICHZEITIGER VERRINGERUNG DER METALLKORROSION

Title (fr)

APPAREIL ET PROCEDE DE TRAITEMENT ELECTROCHIMIQUE D'UN SUBSTRAT REDUISANT LA CORROSION DU METAL

Publication

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Application

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Abstract (en)

[origin: WO2004003663A2] A process tool (200) for electrochemically treating a substrate (201) is configured to reduce the oxygen concentration and/or the sulfur dioxide concentration in the vicinity of the substrate so that corrosion of copper may be reduced. In one embodiment, a substantially inert atmosphere is established within the process tool (200) including a plating reactor by providing a continuous inert gas flow and/or by providing a cover (201) that reduces a gas exchange with the ambient atmosphere. The substantially inert gas atmosphere may also be maintained during further process steps involved in electrochemically treating the substrate including required transportation steps between the individual process steps.

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C25D 7/12

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